

5th IEEE INTERNATIONAL CONFERENCE ON INTERDISCIPLINARY APPROACHES IN TECHNOLOGY AND MANAGEMENT FOR SOCIAL INNOVATION (IEEE IATMSI-2027)

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CALL FOR PAPERS

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IMPORTANT DATES

DECEMBER 20, 2026

Paper Submission Due Date

JANUARY 30, 2027

Review Notification Deadline
(Accept, Reject)

FEBRUARY 15, 2027

Early Bird Registration Due Date

MARCH 20, 2027

Camera-ready Paper Due

MARCH 30, 2027

Last Date of Registration

SCAN FOR WEBSITE, AWARDS, GRANTS, REGISTRATION, SPONSORSHIPS & OTHER DETAILS



If you are interested in joining our review committee, kindly submit your consent via the form application (click here). Application Link: <https://forms.gle/9p6qHaRsFc4VbDgCA>



The 5th IEEE International Conference on Interdisciplinary Approaches in Technology and Management for Social Innovation (IATMSI-2027) will be held from May 20–22, 2027, in Kathmandu, Nepal, in collaboration with the IEEE Madhya Pradesh Section and the IEEE Nepal Section. A globally recognized, Scopus-indexed conference, IATMSI provides an international platform for researchers, academicians, and industry professionals to present advances in Artificial Intelligence, Healthcare, Energy, VLSI Design, Communication Technologies, Smart Systems, Sustainable Innovations, and related areas. With the theme "Enabling the Change! Social Innovation for Sustainable Societies," IATMSI-2027 will be conducted in a hybrid mode, bringing together participants from academia and industry worldwide while offering an opportunity to experience the rich heritage and breathtaking natural beauty of Kathmandu, Nepal.

TRACKS AND TOPICS FOR IEEE IATMSI-2027

Track 1: Innovative Solutions for Healthcare, Biomedical Engineering and Sustainable Development

Biomedical Instrumentation and Sensors; Bioengineering, Bioinformatics, Infection biology, Environmental Biotechnology; IoT and Soft Computing Applications in Healthcare; AI, Blockchain and Cloud computing in Healthcare; Healthcare Mobile and Web Applications & Telemedicine; Accelerating Healthcare with Data and AI to Meet COVID-19 Challenges; Ethics, Privacy, and Security in Healthcare; AI, Blockchain and Cloud computing in Healthcare; Technology and Digital Health; Other Related areas of Healthcare.

Track 2: Power, Control, Energy, and Intelligent Transportation Technologies

Intelligent Transportation, Internet of Vehicles; Control, Communication and Automation Enabled Technologies; Mechatronics and Robotics Technologies; Blockchain, Inter-Vehicle Wireless Communications Technologies; Electric and Hybrid-Electric Vehicles; Power Systems and Smart Grids; Nano-Fluids Dynamics for Industrial Applications; Renewable and Sustainable Energy Solutions; Smart Grid, Electric Vehicle, Battery Management System, Grid integration with RES, Electric actuators, Servo drives, and IoT interfaces; Machine Vibration & Condition Monitoring; Signal Processing for Machine Health Monitoring and RFID 3D Scanning; Intelligent Reflecting Surfaces; Reconfigurable Intelligent Surfaces; Unmanned Aerial Vehicles/Drones Technology; Other Related areas.

Track 3: AI, Data Science, IoT, and Computer Vision-Enabled Technologies

Image Processing and Computational Intelligence in Agriculture; Biotechnology Solutions for Sustainable Agriculture; Applications of Image and Video Processing for Industrial Applications; Machine Learning & AI Approaches to Manufacturing Applications; High-Performance Computing, Cloud Computing, IoT based Technologies; ML, Deep Learning and Natural Language Processing (NLP); Data Privacy and Protection, Cyber Security, Surveillance and Fraud Detection; Applications of AR/VR for Customer Engagement, Application of AI & ML in Management; Other Related areas.

Track 4: Green, Flexible Electronics, VLSI, Communication, and Sensor-Based Technologies

Wireless Sensor Networks, Advances in Sensor Technology; Nanotechnology and Sensor Based Solutions for Environment-Friendly Agriculture; Green Technology and Rural Environmental Concerns; Technology in Agriculture for Sustainable Development; Hybrid Systems, Biosensors; Optical and Wireless Communications; Technologies for 5G and beyond Communication; Antenna Design; VLSI Design, Embedded System and Emerging Technologies for the Social Change; IC Design and Testing, Flexible Electronics and sustainable Technologies; Communication Technologies and Networks, Digital Manufacturing; Signal & Image Processing, LORA Functioning in Industrial Environment; Mobile HMI for Electronic Products; Nanotechnology Based Human-Centered Designs; Other Related areas.

Track 5: IT-enabled Management for Social Innovation

Entrepreneurship, Innovation, with Information Technology; Technological Forecasting and Social Change; Technology Roadmaps for Transition Management; IT Enabled Marketing; Consumer Technology; Big Data Analytics; Business Analytics; Sustainable Manufacturing through IT Enabled Technologies; Paradigm Shift in Human Resource Practices through the use of Digital Technologies; Health Care Management for Healthy Society; Technology-Enabled Financial Management; Other Related areas.

Track 6: Quantum Technologies, Digital Twins, Industry 5.0 and Smart Manufacturing

Quantum Computing, Communications, Sensing and Security; Quantum AI and Emerging Applications; Digital Twin Modeling and Simulation; AI-Driven Digital Twins; Smart Factories and Industry 5.0; Human-Machine Collaboration; Intelligent Manufacturing and Automation; Robotics and Autonomous Systems; Additive Manufacturing and 3D Printing; Smart Supply Chains and Logistics; Industrial Data Analytics and AI; Edge, Cloud, and Digital Manufacturing; Sustainable and Green Manufacturing; Industrial Cybersecurity and Resilience; AR/VR/XR for Industrial Applications; Advanced Monitoring, Control, and Maintenance; Other Related areas.

AWARDS

1. Hardnovate Contest.
2. Rising Researcher Award.
3. Excellence in Research Award
4. IEEE Doctoral Dissertation Award
5. Simulation Excellence Award
6. Best Paper Awards
7. Fellowships (Travel/Registration Grants)

REGISTRATION FEES

Category	Early Bird Registration (Until 15 th Feb. 2027)				Regular Registration (After 15 th Feb. 2027)			
	Indian/Nepali Delegates		International Delegates		Indian/Nepali Delegates		International Delegates	
	IEEE Member	Non-IEEE Member	IEEE Member	Non-IEEE Member	IEEE Member	Non-IEEE Member	IEEE Member	Non-IEEE Member
Tutorial/Workshop Attendee	2500₹	3000₹	80\$	100\$	3000₹	3500₹	100\$	120\$
Student Authors (UG/ PG/ PhD/ Any Other)	6400₹	7500₹	150\$	180\$	7400₹	8500₹	175\$	205\$
Professional Authors (Academician/ Industry/ Any Other)	7600₹	8700₹	180\$	210\$	8600₹	9700₹	210\$	240\$
Co-Authors/ Attendees/ Accompanying Person (without Conference Kit)*	4000₹	5000₹	100\$	120\$	4500₹	5500₹	120\$	140\$
Co-Authors/ Attendees/ Accompanying Person (with Conference Kit)*	5500₹	6500₹	120\$	140\$	6500₹	7500₹	140\$	160\$

SUBMISSION INFORMATION

Authors must submit original, unpublished papers (max 6 pages, IEEE double-column format) via **Microsoft CMT**; non-compliant papers will be rejected without review. Accepted papers require at least one paid registration and presentation at IATMSI 2027 for IEEE Xplore inclusion. <https://iatmsi.iiitm.ac.in/paper-submission/>

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